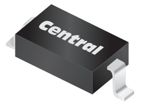
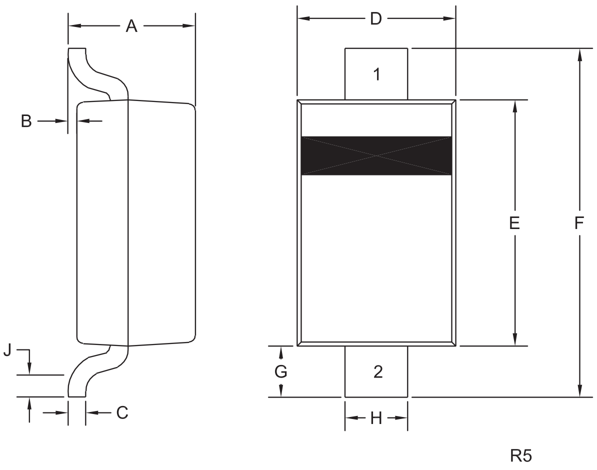
Package Details

SOD-123 Case



Mechanical Drawing



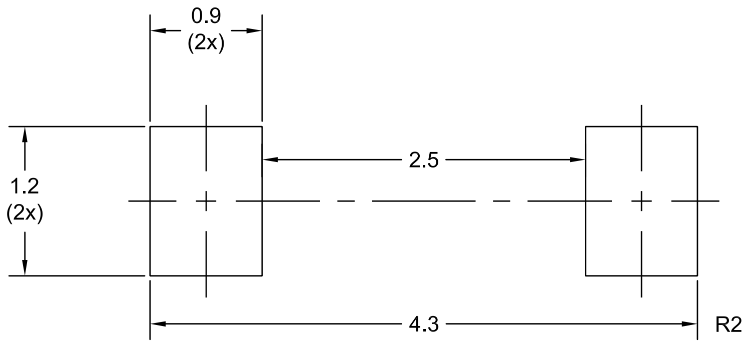
DIMENSIONS				
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	0.037	0.053	0.95	1.35
B	0.000	0.005	0.00	0.12
C	-	0.008	-	0.20
D	0.055	0.071	1.40	1.80
E	0.098	0.110	2.50	2.80
F	0.142	0.154	3.60	3.90
G	0.016	-	0.40	-
H	0.020	0.028	0.50	0.70
J	0.010	-	0.25	-

SOD-123 (REV:R5)

Lead Code:
1) Cathode
2) Anode

Part Marking: 3 Character Alpha/Numeric Code

Mounting Pad Geometry (Dimensions in mm)

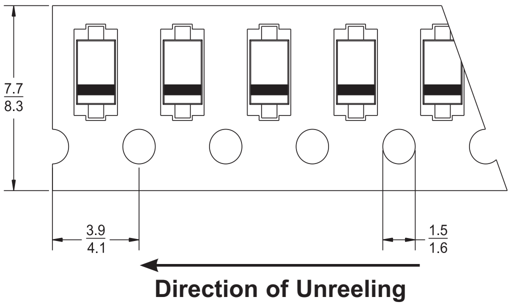


Package Details

SOD-123 Case

Tape Dimensions and Orientation (Dimensions in mm)

Tape Width: 8mm



Devices are taped in
accordance with
Electronic Industries
Association Standard
EIA-481-1-A

Packaging Base

7" Reel = 3,000 pcs.

Reel Labeling Information

Each reel is labeled with the following information:
Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code, Ship Date and Marking Code.

Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
7"	8	24,000	9x9x5	23x23x13	4	2
	17	51,000	9x9x9	23x23x23	7	4
	40	120,000	21x9x9	53x23x23	14	7
	108	324,000	27x9x17	69x23x43	39	18

Ordering Information

- For devices taped and reeled on 7" reels, add TR suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

R4 (5-August 2010)

Material Composition Specification

SOD-123 Case

Device average mass . . . . **10.2 mg**
Fluctuation margin . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.59%	0.06	Si	7440-21-3	0.59%	0.06	5,882
bond wire	gold or copper	0.1%	0.01	Au	7440-57-5	0.1%	0.01	980
				Cu	7440-50-8			
leadframe	alloy 42 w/ silver plating	21.18%	2.16	Fe	7439-89-6	12.27%	1.252	122,745
				Ni	7440-02-0	8.47%	0.864	84,706
				Ag	7440-22-4	0.43%	0.044	4,314
encapsulation*	EMC	77.75%	7.93	silica	7631-86-9	52.87%	5.392	528,669
				epoxy resin	29690-82-2	15.55%	1.586	155,486
				phenol resin	9003-35-4	7.77%	0.793	77,743
				Sb_2O_3	1309-64-4	0.78%	0.079	7,776
				Br	7726-95-6	0.78%	0.079	7,776
	EMC GREEN	77.75%	7.93	silica (fused)	60676-86-0	59.87%	6.106	598,657
				epoxy resin	29690-82-2	7.77%	0.793	77,743
				phenol resin	9003-35-4	7.54%	0.769	75,412
				carbon black	1333-86-4	0.23%	0.024	2,331
				metal hydroxide	1309-42-8	2.33%	0.238	23,308
plating**	tin/lead process	0.39%	0.04	Sn	7440-31-5	0.31%	0.032	3,137
				Pb	7439-92-1	0.08%	0.008	784
	matte tin	0.39%	0.04	Sn	7440-31-5	0.39%	0.04	3,922

*EMC GREEN molding compound is Halogen-Free.
**For Lead Free plating, add suffix "PB FREE" to part number.
For Tin/Lead plating, add suffix "TIN/LEAD" to part number.
No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R5 (16-July 2018)